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Specification for Approval

Customer:	
Model Name:	

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		

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Revision Record

REV NO.	REV DATE	CONTENTS	Note
А	2013-01-08	NEW ISSUE	
В	2013-05-21	Change LCD and IC	
С	2013-08-29	Change Backlight	

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

2. General Information

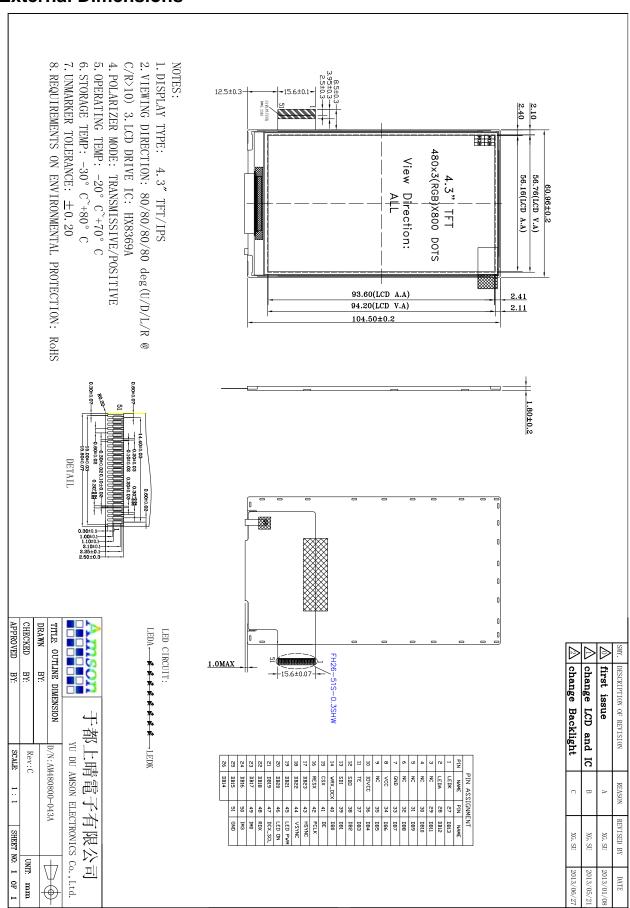
ITEM	STANDARD VALUES	UNITS
LCD type	4.3"TFT	
Dot arrangement	480(RGB)×800	dots
Color filter array	RGB vertical stripe	
Display mode	IPS / Transmission / Normally Black	
Viewing Direction	80/80/80/80 deg(U/D/L/R @ C/R>10)	
Driver IC	HX8369A	
Module size	60.96(W)×104.50(H)×1.8(T)	mm
Active area	56.16(W)×93.6(H)	mm
Dot pitch	0.117(W)×0.117(H)	mm
Interface	8-/ 9-bit i80-series system interface 3-Wire SPI + 16-/18-/24-bit RGB interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	8 White LED In Serial	
Weight	TBD	g



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3. External Dimensions





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4. Interface Description

4. 11	iterrace Di	escription
Pin	Symbol	Description.
1	LEDK	LED backlight (Cathode).
2	LEDA	LED backlight (Anode).
3	NC	No connection.
4	NC	No connection.
5	NC	No connection.
6	NC	No connection.
7	GND	Power ground
8	VCC	Analog supply voltage to the analog circuit.
9	NC	No connection.
10	IOVCC	Logic supply voltage to the logic circuit.
11	TE	Tearing effect output pin to synchronize MCU to frame writing.
12	SDO	Serial output signal in SPI I/F.
13	SDI	Serial input signal in SPI I/F.
14	WRX_DCX	Writes strobe signal to write data when WRX is "Low" in MPU I/F. Date/Command Selection pin in 4-wire SPI I/F.
15	CSX	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.
16	RESX	Reset input pin, Active "L".
17	DB23	
18	DB22	
19	DB21	
20	DB20	
21	DB19	
22	DB18	
23	DB17	
24	DB16	OA bit a smalled bit dissertion of data base for MDU screte re-
25	DB15	24-bit parallel bi-directional data bus for MPU system: 8-bit I/F: DB[7:0] is used.
26	DB14	16-bit I/F: DB[15:0] and DB[8:1] is used.
27	DB13	24-bit I/F: DB[23:0] is used.
28	DB12	
29	DB11	24-bit input data bus for RGB I/F.
30	DB10	16-bit/pixel: DB[20:16]=R[4:0], DB[13:8]=G[5:0] and DB[5:1]=B[4:0];
31	DB09	18-bit/pixel: DB[21:16]=R[5:0], DB[13:8]=G[5:0] and DB[5:0]=B[5:0]; 24-bit/pixel: DB[23:16]=R[7:0], DB[15:8]=G[7:0] and DB[7:0]=B[7:0].
32	DB08	Connect unused pins to GND.
33	DB06	
34	DB07	
35	DB05	
36	DB04	
37	DB03	
38	DB02	
39	DB01	
40	DB00	



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41	DE	Data enable signal in RGB I/F mode
42	PCLK	Pixel clock signal in RGB I/F.
43	HSYNC	Horizontal sync signal in RGB I/F.
44	VSYNC	Vertical sync signal in RGB I/F.
45	LEDPWM	Connect to the external LED driver. If not used, please open this pin.
46	LEDON	Connect to the external LED driver. If not used, please open this pin.
47	DCX_SCL	Display data / command selection in 80-series MPU I/F. A synchronous clock signal in SPI I/F.
48	RDX	Reads strobe signal to write data when RD is "Low" in MPU interface.
49	IMO	System interface Mode IM[3] IM[0]=00, i80-system 8-bit MPU interface : DB[7:0] is used.
50	IM3	IM[3] IM[0]=01, i80-system 9-bit MPU interface : DB[9:0] is used. IM[3] IM[0]=11, 3-wire SPI + RGB interface
51	GND	Power ground

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	5.5	V
Analog Supply Voltage	VCC	-0.3	3.6	V
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

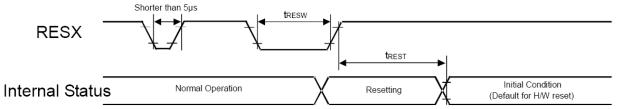
6. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	٧	-
Analog Supply Voltage	VCC	2.3	2.8	3.3	٧	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	٧	Digital input pins
Input Low Voltage	V _{IL}	-0.3	-	0.3IOVCC	٧	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	-	IOVCC	V	Digital output pins
Output Low Voltage	V_{OL}	0	-	0.2IOVCC	V	Digital output pins
I/O Leak Current	lu	-1.0	ı	1.0	mA	-

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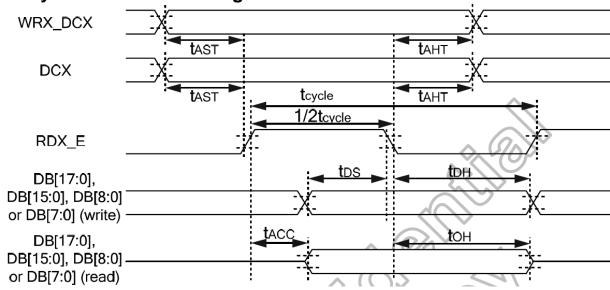
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7. Timing Characteristics7.1 Reset Timing Characteristics



Symbol	Parameter	Related pins	Min.	Тур.	Max.	Note	Unit
t _{RESW}	Reset low pulse width ⁽¹⁾	RESX	10	-	الح -	-	μs
	Reset complete time ⁽²⁾	-	5	- <		When reset is applied during Sleep In mode	ms
I _{REST}	Reset complete time	-	120	9		When reset is applied during Sleep Out mode	ms

7.2 i80-System Interface Timing Characteristics

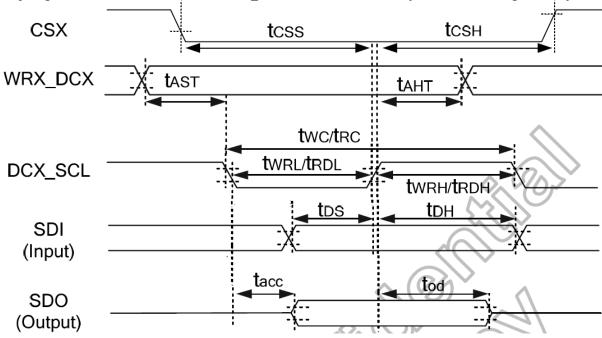


Signal	Symbol	Parameter	Min.	Max.	Unit	Description
WRX_DCX or DCX_SCL	t ast t aht	Address setup time Address hold time (Write/Read)	10 10		ns	-
		System clock cycle time read register	100	790	ns	-
CSX or		Read GRAM	350	790	ns	-
RDX E	t cycle	Write register	100	790	ns	-
_		Write GRAM @ SLPOUT	33	790	ns	=
		Write GRAM @ SLPIN	100	790	ns	-
	tos	Data setup time	15	-		For maximum
DB23-DB0	tон	Data hold time	25	-	ns	CL=30pF
	tacc	Read access time	10	-	113	For minimum CL=8pF
	t oH	Output disable time	10	-		

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7.3 Display Serial Interface Timing Characteristics (3-line SPI system)

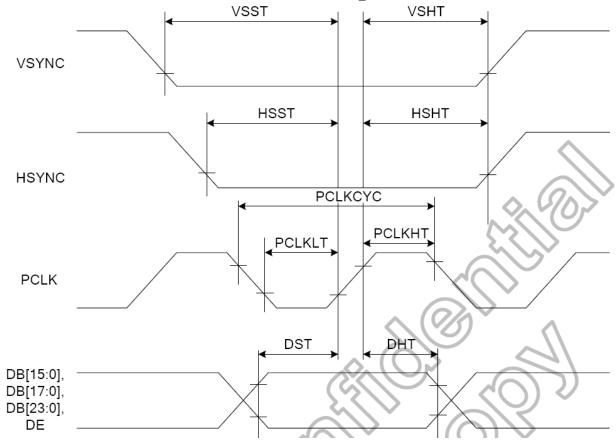


Signal	Symbol	Parameter	Min.	Max.	Unit	Description
CSX	tcss tcsн	Chip select setup time (Write) Chip select setup time (Read)	40 40		ns	-
WRX_DCX	tast taht	Address setup time Address hold time (Write/Read)	10 10		ns	-
DCX_SCL (Write)	twc twrh twrl	Write cycle Control pulse "H" duration Control pulse "L" duration	100 40 40		ns	-
DCX_SCL (Read)	trc trdh trdl	Read cycle Control pulse "H" duration Control pulse "L" duration	150 60 60	- - -	ns	-
SDI/SDO (Input)	tos tor	Data setup time Data hold time	30 30	-	ns	For maximum C∟=30pF
SDI/SDO (Output)	tracc tod	Read access time Output disable time	10 10	- 50	ns	For minimum C∟=8pF

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7.4 Parallel 24/18/16-bit RGB Interface Timing Characteristics



Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Vertical sync. setup time	VSST	∧ (-())	5	-	-	ns
Vertical sync. hold time	VSHT		5	-	-	ns
Horizontal sync. setup time	HSST		5	-	-	ns
Horizontal sync. hold time	HSHT	-	5	-	1	ns
Pixel clock cycle when RGB I/F is running	PCLKCYC	VRR ⁽⁵⁾ = Min . 50 Hz Max. 70 Hz	31 ⁽³⁾	-	49.2 ⁽⁴⁾	ns
Pixel clock low time	PCLKLT	-	5	-	-	ns
Pixel clock high time	PCLKHT	-	5	-	-	ns
Data setup time DB[23:0]	DST	-	5	-	-	ns
Data hold time DB[23:0]	DHT	-	5	-	-	ns



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8. Backlight Characteristics



Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	23.2	25.6	28.0	V	lf=20mA
Supply Current	If		20	30	mA	
Luminous Intensity for LCM		250	300		Cd/m ²	If=20mA
Uniformity for LCM		80			%	If=20mA
Life Time		50000			Hr	If=20mA
Backlight Color	White					



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9. Optical Characteristics

Optical characteristics are determined after the unit has been 'ON' and stable for approximately 30 minutes in a dark environment at 25 °C. The values specified are at an approximate distance 50cm from the TFT-LCD surface at a viewing angle of Φ and θ equal to 0°. Measurement condition: Refer to next pages (LED back light with 20 mA/1 ea)

*1): with LGD Polarizer;

*2): Only Color Filter glass

). Offiny Color Filter glass							
Parameter	Symbol	Values			Unit	Notos	
Parameter	Symbol	Min	Тур	Max	Ullit	Notes	
*1) Threshold Voltage	Vsat	3.65	3.9	4.15	V	Fig 2	
*1) Threshold Voltage	Vth	1.8	2.0	2.2	V	Fig.2	
*1) Transmittance	T(%)	3.7	4.1	-	%	Fig.1	
*1) Contrast Ratio	C/R	650	800	-			
*1) Response Time	Tr+Tf	-	35	45	msec	Fig.3	
	Rx	0.640	0.660	0.680			
	Ry	0.297	0.317	0.337			
	Gx	0.240	0.260	0.280			
*2) CIE Color Coordinate	Gy	0.555	0.575	0.595			
-7 CIE Color Coordinate	Bx	0.121	0.141	0.161			
	Ву	0.055	0.075	0.095			
	Wx	0.275	0.295	0.315			
	Wy	0.297	0.317	0.337			
*1)	ΘΙ	70	80	-			
	Θr	70	80	-	Dammas	C/R>10	
*1) Viewing Angle	Θu	70	80	-	Degree	Fig.4	
	Θd	70	80	-			

Notes:

1. Contrast Ratio (CR) is defined mathematically as:

Contrast Ratio = Surface Luminance with all white pixels
Surface Luminance with all black pixels

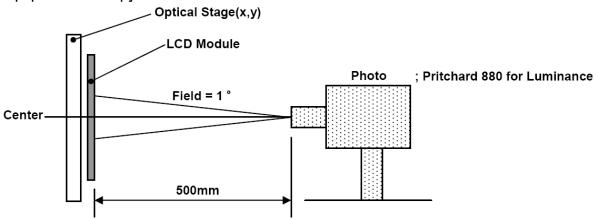
- 2. Surface luminance is the center point across the TFT-LCD surface 500mm from the surface with all pixels displaying white. For more information see FIG 1.
- 3. Response time is the time required for the display to transition from white to black (Rise Time, Tr) and from black to white (Falling Time, Tf). For additional information see FIG 3.
- 4. Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the TFT-LCD surface. For more information see FIG 5.
- 5. Optimum contrast is obtained by adjusting the TFT-LCD threshold voltage (Vth & Vsat).

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FIG. 1 Optical Characteristic Measurement Equipment and Method

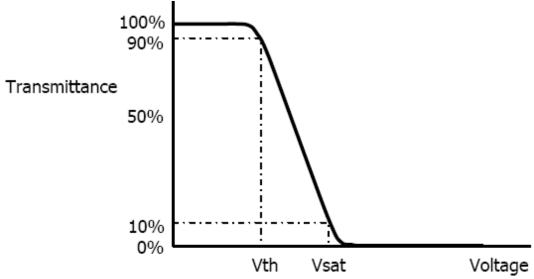
[Test Equipment Set Up]



Measuring Condition;

- -Measuring surroundings: Darkroom
- -Measuring temperature: Ta=25°C
- -Adjust operating voltage to get optimum contrast at the center of the display.
- -Measured value at the center point of LCD panel after more than 30 minutes while backlight turning on.

FIG. 2 The definition of Vth and Vsat

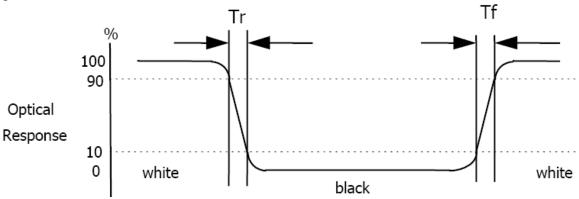


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FIG. 3 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".



* Voltage conditions for Response time

Vgate: 20V DC Vdata: 0V~5V DC Vcom: 0V (Ground)

FIG. 4 The definition of viewing angle: <dimension of viewing angle range>

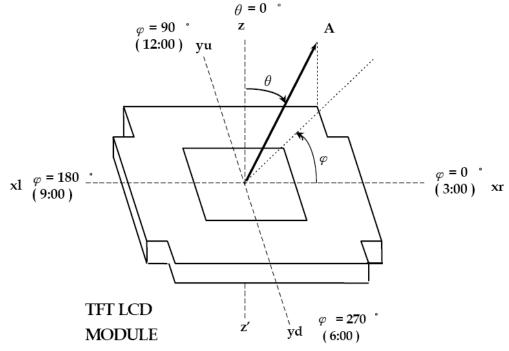
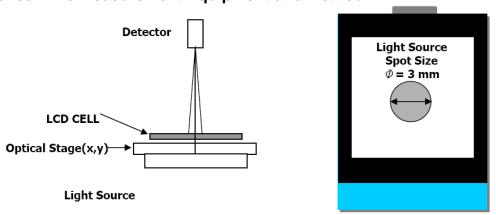


FIG. 5 Response Time Measurement Equipment and Method





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10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
	High Temperature Storage	80°C±2°C×200Hours	
	Low Temperature Storage	-30°C±2°C×200Hours	
	High Temperature Operating	70°C±2°C×120Hours	Inspection after 2~4hours storage at room temperature,
	Low Temperature Operating	-20°C±2°C×120Hours	the samples should be free from defects: 1, Air bubble in the
	Temperature Cycle(Storage)	$ \begin{array}{c} -20^{\circ}\text{C} & \Longrightarrow 25^{\circ}\text{C} & \Longrightarrow 70^{\circ}\text{C} \\ (30\text{min}) & (5\text{min}) & (30\text{min}) \\ \hline & 1\text{cycle} \\ & \text{Total 10cycle} \end{array} $	LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack.
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	6, Current IDD is twice higher than initial value.
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7, The surface shall be free from damage. 8, The electric characteristic requirements shall be
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance $> 10M\Omega$)should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



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11. Inspection Standard

This standard apply to C-STN/TFT module

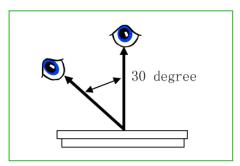
1. Spot check plan:

According to spot check level ${\rm II}$,MIL-STD-105D Level ${\rm II}$,the rank of accept or reject is below:

3A、2A: major non-conformance: AQL 0.25 minor non-conformance: AQL 0.4

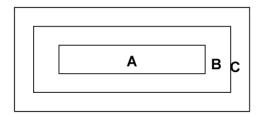
1A: major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

2. Inspection condition:



Under daylight lamp 20 \sim 40W, product distance inspector 'eye 30cm,incline degree 30° $_{\circ}$

3. LCD area define:



Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assembly

Remark: non-conformance at area C, but is OK that isn't influence reliability of product & assembly by customer.



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4. Inspection standard

4.1 Major non-conformance

NO.	Item Inspection standard				
4.1.1	Function non-conformance				
4.1.2	miss	No matter miss what component			
4.1.3	Out of size	Module dimension out of spec			

4.2 Appearance non-conformance

NO.	Item			Inspe	ection s	tanda	rd		Rate
		dot non-conformance define Φ $\Phi = \frac{-+y}{2} x ($							
	A grade Most approve q'ty				\neg				
	Black or	size (mm	rea	Α	wost ap	B	C		
4.2.1	white spot (power	Ф≤0.1	0		ignore				Minor
	on)	0.10<Φ≤	0.15		4				
		0.15<Φ≤	≤0.20 2 ignore		9				
		0.20<Φ≤	0.25 1						
		0.25<	Φ	0					
		Most approv	ve 4 da	mages	s, dot to	dot ≥	≥10mm		
		A grade	(mm)		Ī	Most	approve	a'tv	1
		L(length)	<u> </u>	ridth)	Α		В	C	
	ignore	ignore	W≤	0.03	ignore		,		
4.2.2 Black or white line (power on)	L≤5.0		3< 0.05		3			Minor	
	· -	L≤3.0		5< 0.07	ignore 2	ignore			
			0.07	′ <w< td=""><td></td><td>at with</td><td>dot nance</td><td></td><td></td></w<>		at with	dot nance		
		Most approv	ve 3 da	mages	s, line to	line	≥10mm		



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4.2.3	Polarizer position	Polarizer attach Polarizer must unless)		allow out of LCD. area (special require	Minor	
4.2.4	LCD non-conform ance	(i) crash at side (range) X ≤3.0 Crash dis (ii) commonly surf X ≤2.0 (iii) crack Disallow extend	Y S Sallow extend to IT Face scathe Y	Z ignore	Minor	
4.2.5	Contrast voltage warp	VOP/VIcd voltage of confirmed sample \pm 0.15V				
4.2.6	color	Color & luminance	of module scope r	eference spec	Minor	
4.2.7	Cross talk	Reference confirme	ed limit sample		Minor	



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12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to VDD or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the maximum operating temperature, 50%Rh or less is required.



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12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

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14. Packing Method

